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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	69
Number of Gates	6000
Voltage - Supply	3V ~ 3.6V, 4.5V ~ 5.5V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	80-TQFP
Supplier Device Package	80-VQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a40mx04-vq80i

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Table 33 • Timing Parameters for 33 MHz PCI

Symbol	Parameter	PCI		A42MX24		A42MX36		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{SU(PTP)}$	Input Set-Up Time to CLK—Point-to-Point	10, 12 ²	–	1.5	–	1.5	–	ns
t_H	Input Hold to CLK	0	–	0	–	0	–	ns

1. TOFF is system dependent. MX PCI devices have 7.4 ns turn-off time, reflection is typically an additional 10 ns.
2. REQ# and GNT# are point-to-point signals and have different output valid delay and input setup times than do bussed signals. GNT# has a setup of 10; REW# has a setup of 12.

3.11.6.1 Timing Characteristics

The following tables list the timing characteristics.

**Table 34 • A40MX02 Timing Characteristics (Nominal 5.0 V Operation)
(Worst-Case Commercial Conditions, VCC = 4.75 V, T_J = 70°C)**

Parameter / Description	–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
Logic Module Propagation Delays												
t_{PD1}	Single Module		1.2		1.4		1.6		1.9		2.7	ns
t_{PD2}	Dual-Module Macros		2.7		3.1		3.5		4.1		5.7	ns
t_{CO}	Sequential Clock-to-Q		1.2		1.4		1.6		1.9		2.7	ns
t_{GO}	Latch G-to-Q		1.2		1.4		1.6		1.9		2.7	ns
t_{RS}	Flip-Flop (Latch) Reset-to-Q		1.2		1.4		1.6		1.9		2.7	ns
Logic Module Predicted Routing Delays¹												
t_{RD1}	FO = 1 Routing Delay		1.3		1.5		1.7		2.0		2.8	ns
t_{RD2}	FO = 2 Routing Delay		1.8		2.1		2.4		2.8		3.9	ns
t_{RD3}	FO = 3 Routing Delay		2.3		2.7		3.0		3.6		5.0	ns
t_{RD4}	FO = 4 Routing Delay		2.9		3.3		3.7		4.4		6.1	ns
t_{RD8}	FO = 8 Routing Delay		4.9		5.7		6.5		7.6		10.6	ns
Logic Module Sequential Timing²												
t_{SUD}	Flip-Flop (Latch) Data Input Set-Up		3.1		3.5		4.0		4.7		6.6	ns
t_{HD}^3	Flip-Flop (Latch) Data Input Hold		0.0		0.0		0.0		0.0		0.0	ns
t_{SUENA}	Flip-Flop (Latch) Enable Set-Up		3.1		3.5		4.0		4.7		6.6	ns
t_{HENA}	Flip-Flop (Latch) Enable Hold		0.0		0.0		0.0		0.0		0.0	ns
t_{WCLKA}	Flip-Flop (Latch) Clock Active Pulse Width		3.3		3.8		4.3		5.0		7.0	ns
t_{WASYN}	Flip-Flop (Latch) Asynchronous Pulse Width		3.3		3.8		4.3		5.0		7.0	ns
t_A	Flip-Flop Clock Input Period		4.8		5.6		6.3		7.5		10.4	ns
f_{MAX}	Flip-Flop (Latch) Clock Frequency (FO = 128)		181		168		154		134		80	MHz

Table 34 • A40MX02 Timing Characteristics (Nominal 5.0 V Operation) (continued)
(Worst-Case Commercial Conditions, VCC = 4.75 V, T_J = 70°C)

Parameter / Description		-3 Speed		-2 Speed		-1 Speed		Std Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Input Module Propagation Delays												
t _{INYH}	Pad-to-Y HIGH		0.7		0.8		0.9		1.1		1.5	ns
t _{INYL}	Pad-to-Y LOW		0.6		0.7		0.8		1.0		1.3	ns
Input Module Predicted Routing Delays¹												
t _{IRD1}	FO = 1 Routing Delay		2.1		2.4		2.2		3.2		4.5	ns
t _{IRD2}	FO = 2 Routing Delay		2.6		3.0		3.4		4.0		5.6	ns
t _{IRD3}	FO = 3 Routing Delay		3.1		3.6		4.1		4.8		6.7	ns
t _{IRD4}	FO = 4 Routing Delay		3.6		4.2		4.8		5.6		7.8	ns
t _{IRD8}	FO = 8 Routing Delay		5.7		6.6		7.5		8.8		12.4	ns
Global Clock Network												
t _{CKH}	Input Low to HIGH	FO = 16	4.6		5.3		6.0		7.0		9.8	ns
		FO = 128	4.6		5.3		6.0		7.0		9.8	
t _{CKL}	Input High to LOW	FO = 16	4.8		5.6		6.3		7.4		10.4	ns
		FO = 128	4.8		5.6		6.3		7.4		10.4	
t _{PWH}	Minimum Pulse Width HIGH	FO = 16	2.2		2.6		2.9		3.4		4.8	ns
		FO = 128	2.4		2.7		3.1		3.6		5.1	
t _{PWL}	Minimum Pulse Width LOW	FO = 16	2.2		2.6		2.9		3.4		4.8	ns
		FO = 128	2.4		2.7		3.01		3.6		5.1	
t _{CKSW}	Maximum Skew	FO = 16	0.4		0.5		0.5		0.6		0.8	ns
		FO = 128	0.5		0.6		0.7		0.8		1.2	
t _P	Minimum Period	FO = 16	4.7		5.4		6.1		7.2		10.0	ns
		FO = 128	4.8		5.6		6.3		7.5		10.4	
f _{MAX}	Maximum Frequency	FO = 16	188		175		160		139		83	MHz
		FO = 128	181		168		154		134		80	

Table 36 • A40MX04 Timing Characteristics (Nominal 5.0 V Operation) (continued)(Worst-Case Commercial Conditions, VCC = 4.75 V, T_J = 70°C)

Parameter / Description	-3 Speed		-2 Speed		-1 Speed		Std Speed		-F Speed		Units
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
CMOS Output Module Timing¹											
t _{DLH}	Data-to-Pad HIGH	3.9	4.5	5.1	6.05	8.5	ns				
t _{DHL}	Data-to-Pad LOW	3.4	3.9	4.4	5.2	7.3	ns				
t _{ENZH}	Enable Pad Z to HIGH	3.4	3.9	4.4	5.2	7.3	ns				
t _{ENZL}	Enable Pad Z to LOW	4.9	5.6	6.4	7.5	10.5	ns				
t _{ENHZ}	Enable Pad HIGH to Z	7.9	9.1	10.4	12.2	17.0	ns				
t _{ENLZ}	Enable Pad LOW to Z	5.9	6.8	7.7	9.0	12.6	ns				
d _{TLH}	Delta LOW to HIGH	0.03	0.04	0.04	0.05	0.07	ns/pF				
d _{THL}	Delta HIGH to LOW	0.02	0.02	0.03	0.03	0.04	ns/pF				

1. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.
2. Set-up times assume fanout of 3. Further testing information can be obtained from the Timer utility
3. The hold time for the DFME1A macro may be greater than 0 ns. Use the Timer utility from the Designer software to check the hold time for this macro.
4. Delays based on 35 pF loading

Table 37 • A40MX04 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, VCC = 3.0 V, T_J = 70°C)

Parameter / Description	-3 Speed		-2 Speed		-1 Speed		Std Speed		-F Speed		Units
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Logic Module Propagation Delays											
t _{PD1}	Single Module	1.7	2.0	2.3	2.7	3.7	ns				
t _{PD2}	Dual-Module Macros	3.7	4.3	4.9	5.7	8.0	ns				
t _{CO}	Sequential Clock-to-Q	1.7	2.0	2.3	2.7	3.7	ns				
t _{GO}	Latch G-to-Q	1.7	2.0	2.3	2.7	3.7	ns				
t _{RS}	Flip-Flop (Latch) Reset-to-Q	1.7	2.0	2.3	2.7	3.7	ns				
Logic Module Predicted Routing Delays¹											
t _{RD1}	FO = 1 Routing Delay	1.9	2.2	2.5	3.0	4.2	ns				
t _{RD2}	FO = 2 Routing Delay	2.7	3.1	3.5	4.1	5.7	ns				
t _{RD3}	FO = 3 Routing Delay	3.4	3.9	4.4	5.2	7.3	ns				
t _{RD4}	FO = 4 Routing Delay	4.1	4.8	5.4	6.3	8.9	ns				
t _{RD8}	FO = 8 Routing Delay	7.1	8.1	9.2	10.9	15.2	ns				
Logic Module Sequential Timing²											
t _{SUD}	Flip-Flop (Latch) Data Input Set-Up	4.3	5.0	5.6	6.6	9.2	ns				
t _{HD} ³	Flip-Flop (Latch) Data Input Hold	0.0	0.0	0.0	0.0	0.0	ns				
t _{SUENA}	Flip-Flop (Latch) Enable Set-Up	4.3	5.0	5.6	6.6	9.2	ns				
t _{HENA}	Flip-Flop (Latch) Enable Hold	0.0	0.0	0.0	0.0	0.0	ns				

Table 60 • BG272

BG272	
Pin Number	A42MX36 Function
V16	I/O
V17	I/O
V18	SDO, TDO, I/O
V19	I/O
V20	I/O
W1	GND
W2	GND
W3	I/O
W4	TMS, I/O
W5	I/O
W6	I/O
W7	I/O
W8	WD, I/O
W9	WD, I/O
W10	I/O
W11	I/O
W12	I/O
W13	WD, I/O
W14	I/O
W15	I/O
W16	WD, I/O
W17	I/O
W18	WD, I/O
W19	GND
W20	GND
Y1	GND
Y2	GND
Y3	I/O
Y4	TDI, I/O
Y5	WD, I/O
Y6	I/O
Y7	QCLKA, I/O
Y8	I/O
Y9	I/O
Y10	I/O
Y11	I/O
Y12	I/O